

Product Description

Shin-Etsu's KE-1875 is a single component, heat cured, thixotropic adhesive that will cure to form a tough, durable elastomer. KE-1875 exhibits excellent, unprimed adhesion to metals, plastics, glass, and ceramics and has a reduced level of low molecular weight siloxanes to reduce off gassing after cure.

Product Features

- Single component
- Heat cured
- Thixotropic fluid
- Reduced low molecular weight siloxanes

Typical Applications

- Form-in-place gasketing
- Sealing electronics

Typical Properties

Type	Adhesive/Sealant
Cure Type	Addition
One/Two Component	One
Cold Storage	Y
Low Molecular Weight Siloxane Stripped?	Y
Color	Black
Density @ 23C (g/cm ³)	1.06
Viscosity (Pa·s)	80.00
Cure Conditions	1hr @ 120C
Shore A Hardness	27
Tensile Strength (MPa)	2.40
% Elongation	390
Shear Strength (MPa)	2.1
Volume Resistivity (TΩ·cm)	1.0
Dielectric Strength (kV/mm)	24
Usable Temperature Range (C)	-40 to +180

Note: Values are not for specification purposes.

Warranty- The information and data contained herein are believed to be accurate and reliable; however it is the user's responsibility to determine suitability of use. Since Shin-Etsu Silicones, Inc. cannot know all of the uses to which its products may be put or the conditions of use, it makes no warranties concerning the fitness or suitability of its products for a particular use or purpose. You should thoroughly test any proposed use of our products and independently conclude satisfactory performance in your application. Likewise, if the manner in which our products are used requires governmental approval or clearance, you must obtain it. Shin-Etsu Silicones, Inc. warrants only that its products will meet its specifications. There is no warranty of merchantability of fitness of use, nor any other expressed or implied warranties. The user's exclusive remedy and Shin-Etsu Silicones, Inc.'s sole liability is limited to refund of the price or replacement of any product shown to be otherwise than as warranted. Shin-Etsu Silicones, Inc. will not be liable for incidental or consequential damages of any kind. Suggestions of uses should not be taken as inducements to infringe any patents.